

Claims

Claims 1-11 (canceled)

12. (currently amended) An electronic package comprising:  
a device carrier including a metal surface;  
at least a semiconductor unit including at least an electrode; and  
at least an interconnection portion including a first part and a second part, said first part ~~having one end on~~ spanning between said metal surface and ~~another end on~~ said semiconductor unit, said second part ~~having one end on~~ spanning between said metal surface and ~~another end on~~ the electrode of said semiconductor unit, said second part being wrapped by said first part, said first part having a melting point lower than that of said second part ~~and surrounding~~ and adhering to said second part.
13. (original) The electronic package according to claim 12 wherein said interconnection portion electrically connects said metal surface and said semiconductor unit.
14. (original) The electronic package according to claim 12 wherein said interconnection portion mechanically connects said device carrier and said semiconductor unit.
15. (original) The electronic package according to claim 12 wherein said first part contains more tin than lead, while said second part contains more lead than tin.
16. (original) The electronic package according to claim 12 wherein said device

carrier is a lead frame.

17. (currently amended) The electronic package according to claim 12 wherein said device carrier is a lead frame ~~including an inner lead~~ enclosed by said metal surface.

18. (currently amended) The electronic package according to claim 12 wherein said second part contains materials for controlling the solder wettability between said first part and ~~said second part in case said first part is in a fluid state is sealed by said first part, said device carrier, and said semiconductor unit.~~

19. (currently amended) The electronic package according to claim 12 wherein said first part contains materials ~~for~~ by which the solder wettability between said first part and said second part ~~be~~ is controlled by said second part ~~in case said first part is in a fluid state.~~

20. (currently amended) The electronic package according to claim 12 wherein ~~said another end of said first part has an end~~ partially contacts contacting the electrode of said semiconductor unit and partially contacts contacting an area which is part of said semiconductor unit and which surrounds the electrode of said semiconductor unit.